

CMLT2207G

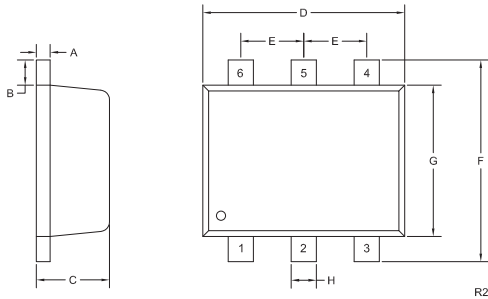
**SURFACE MOUNT SILICON
DUAL, COMPLEMENTARY
TRANSISTOR**



ELECTRICAL CHARACTERISTICS - Continued:

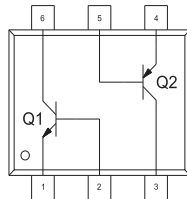
SYMBOL	TEST CONDITIONS	NPN (Q1)		PNP (Q2)		UNITS
		MIN	MAX	MIN	MAX	
f_T	$V_{CE}=20V, I_C=20mA, f=100MHz$	300	-	-	-	MHz
f_T	$V_{CE}=20V, I_C=50mA, f=100MHz$	-	-	200	-	MHz
C_{ob}	$V_{CB}=10V, I_E=0, f=1.0MHz$	-	8.0	-	8.0	pF
C_{ib}	$V_{EB}=0.5V, I_C=0, f=1.0MHz$	-	25	-	-	pF
C_{ib}	$V_{EB}=2.0V, I_C=0, f=1.0MHz$	-	-	-	30	pF
h_{ie}	$V_{CE}=10V, I_C=1.0mA, f=1.0kHz$	2.0	8.0	-	-	k Ω
h_{ie}	$V_{CE}=10V, I_C=10mA, f=1.0kHz$	0.25	1.25	-	-	k Ω
h_{re}	$V_{CE}=10V, I_C=1.0mA, f=1.0kHz$	-	8.0	-	-	x10 ⁻⁴
h_{re}	$V_{CE}=10V, I_C=10mA, f=1.0kHz$	-	4.0	-	-	x10 ⁻⁴
h_{fe}	$V_{CE}=10V, I_C=1.0mA, f=1.0kHz$	50	300	-	-	
h_{fe}	$V_{CE}=10V, I_C=10mA, f=1.0kHz$	75	375	-	-	
h_{oe}	$V_{CE}=10V, I_C=1.0mA, f=1.0kHz$	5.0	35	-	-	μS
h_{oe}	$V_{CE}=10V, I_C=10mA, f=1.0kHz$	25	200	-	-	μS
$rb'C_C$	$V_{CB}=10V, I_E=20mA, f=31.8MHz$	-	150	-	-	ps
NF	$V_{CE}=10V, I_C=100\mu A, R_S=1.0k\Omega, f=1.0kHz$	-	4.0	-	-	dB
t_{on}	$V_{CC}=30V, V_{BE}=0.5V, I_C=150mA, I_{B1}=15mA$	-	-	-	45	ns
t_d	$V_{CC}=30V, V_{BE}=0.5V, I_C=150mA, I_{B1}=15mA$	-	10	-	10	ns
t_r	$V_{CC}=30V, V_{BE}=0.5V, I_C=150mA, I_{B1}=15mA$	-	25	-	40	ns
t_{off}	$V_{CC}=6.0V, I_C=150mA, I_{B1}=I_{B2}=15mA$	-	-	-	100	ns
t_s	$V_{CC}=30V, I_C=150mA, I_{B1}=I_{B2}=15mA$	-	225	-	-	ns
t_s	$V_{CC}=6.0V, I_C=150mA, I_{B1}=I_{B2}=15mA$	-	-	-	80	ns
t_f	$V_{CC}=30V, I_C=150mA, I_{B1}=I_{B2}=15mA$	-	60	-	-	ns
t_f	$V_{CC}=6.0V, I_C=150mA, I_{B1}=I_{B2}=15mA$	-	-	-	30	ns

SOT-563 CASE - MECHANICAL OUTLINE



SYMBOL	DIMENSIONS			
	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.0027	0.007	0.07	0.18
B	0.008		0.20	
C	0.017	0.024	0.45	0.60
D	0.059	0.067	1.50	1.70
E	0.020		0.50	
F	0.059	0.067	1.50	1.70
G	0.043	0.051	1.10	1.30
H	0.006	0.012	0.15	0.30

SOT-563 (REV: R2)



- LEAD CODE:**
- 1) Emitter Q1
 - 2) Base Q1
 - 3) Collector Q2
 - 4) Emitter Q2
 - 5) Base Q2
 - 6) Collector Q1
- MARKING CODE: L7G**

R5 (29-June 2015)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix " TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix " PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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